

NC7S08 TinyLogic™ HS 2-Input AND Gate

General Description

The NC7S08 is a single 2-Input high performance CMOS AND Gate. Advanced Silicon Gate CMOS fabrication assures high speed and low power circuit operation over a broad V_{CC} range. ESD protection diodes inherently guard both inputs and output with respect to the V_{CC} and GND rails. Three stages of gain between inputs and outputs assures high noise immunity and reduced sensitivity to input edge rate.

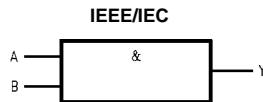
Features

- Space saving SOT23 or SC70 5-lead package
- Ultra small MicroPak™ leadless package
- High Speed; t_{PD} 3.5 ns typ
- Low Quiescent Power; $I_{CC} < 1 \mu A$
- Balanced Output Drive; 2 mA I_{OL} , -2 mA I_{OH}
- Broad V_{CC} Operating Range; 2V-6V
- Balanced Propagation Delays
- Specified for 3V operation

Ordering Code:

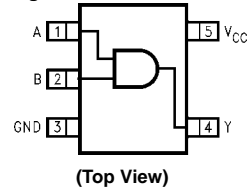
Order Number	Package Number	Product Code Top Mark	Package Description	Supplied As
NC7S08M5X	MA05B	7S08	5-Lead SOT23, JEDEC MO-178, 1.6mm	3k Units on Tape and Reel
NC7S08P5X	MAA05A	S08	5-Lead SC70, EIAJ SC-88a, 1.25mm Wide	3k Units on Tape and Reel
NC7S08L6X	MAC06A	PP	6-Lead MicroPak, 1.0mm Wide	5k Units on Tape and Reel

Logic Symbol



Connection Diagrams

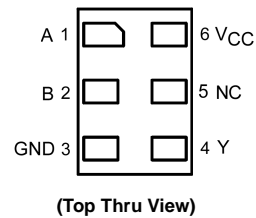
Pin Assignments for SC70 and SOT23



Pin Descriptions

Pin Names	Description
A, B	Inputs
Y	Output
NC	No Connect

Pad Assignments for MicroPak



Function Table

$Y = AB$

Inputs		Output
A	B	Y
L	L	L
L	H	L
H	L	L
H	H	H

H = HIGH Logic Level L = LOW Logic Level

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Absolute Maximum Ratings(Note 1)

Supply Voltage (V_{CC})	-0.5V to +7.0V
DC Input Diode Current (I_{IK})	
@ $V_{IN} \leq -0.5V$	-20 mA
@ $V_{IN} \geq V_{CC} + 0.5V$	+20 mA
DC Input Voltage (V_{IN})	-0.5V to $V_{CC} + 0.5V$
DC Output Diode Current (I_{OK})	
@ $V_{OUT} < -0.5V$	-20 mA
@ $V_{OUT} > V_{CC} + 0.5V$	+20 mA
DC Output Voltage (V_{OUT})	-0.5V to $V_{CC} + 0.5V$
DC Output Source	
or Sink Current (I_{OUT})	± 12.5 mA
DC V_{CC} or Ground Current	
per Output Pin (I_{CC} or I_{GND})	± 25 mA
Storage Temperature (T_{STG})	-65°C to +150°C
Junction Temperature (T_J)	150°C
Lead Temperature (T_L);	
(Soldering, 10 seconds)	260°C
Power Dissipation (P_D) @+85°C	
SOT23-5	200 mW
SC70-5	150 mW

Recommended Operating Conditions (Note 2)

Supply Voltage (V_{CC})	2.0V to 6.0V
Input Voltage (V_{IN})	0V to V_{CC}
Output Voltage (V_{OUT})	0V to V_{CC}
Operating Temperature (T_A)	-40°C to +85°C
Input Rise and Fall Time (t_r, t_f)	
V_{CC} @ 2.0V	0 to 1000 ns
V_{CC} @ 3.0V	0 to 750 ns
V_{CC} @ 4.5V	0 to 500 ns
V_{CC} @ 6.0V	0 to 400 ns
Thermal Resistance (θ_{JA})	
SOT23-5	300°C/W
SC70-5	425°C/W

Note 1: Absolute maximum ratings are those values beyond which damage to the device may occur. The databook specifications should be met, without exception, to ensure that the system design is reliable over its power supply, temperature, and output/input loading variables. Fairchild does not recommend operation of circuits outside databook specifications.

Note 2: Unused inputs must be held HIGH or LOW. They may not float.

DC Electrical Characteristics

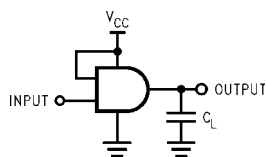
Symbol	Parameter	V_{CC} (V)	$T_A = +25^\circ\text{C}$			$T_A = -40^\circ\text{C to } +85^\circ\text{C}$		Units	Conditions	
			Min	Typ	Max	Min	Max			
V_{IH}	HIGH Level Input Voltage	2.0	1.50			1.50		V		
		3.0-6.0	0.7 V_{CC}			0.7 V_{CC}				
V_{IL}	LOW Level Input Voltage	2.0		0.50		0.50		V		
		3.0-6.0		0.3 V_{CC}		0.3 V_{CC}				
V_{OH}	HIGH Level Output Voltage	2.0	1.90	2.0		1.90		V	$I_{OH} = -20 \mu\text{A}$ $V_{IN} = V_{IH}$	
		3.0	2.90	3.0		2.90				
		4.5	4.40	4.5		4.40				
		6.0	5.90	6.0		5.90				
			3.0	2.68	2.85		2.63		V	$V_{IN} = V_{IH}$ $I_{OH} = -1.3 \text{ mA}$ $I_{OH} = -2 \text{ mA}$ $I_{OH} = -2.6 \text{ mA}$
			4.5	4.18	4.35		4.13			
			6.0	5.68	5.85		5.63			
V_{OL}	LOW Level Output Voltage	2.0		0.0	0.10		0.10	V	$I_{OL} = 20 \mu\text{A}$ $V_{IN} = V_{IL}$	
		3.0		0.0	0.10		0.10			
		4.5		0.0	0.10		0.10			
		6.0		0.0	0.10		0.10			
			3.0		0.1	0.26		0.33	V	$V_{IN} = V_{IH} \text{ or } V_{IL}$ $I_{OH} = 1.3 \text{ mA}$ $I_{OL} = 2 \text{ mA}$ $I_{OL} = 2.6 \text{ mA}$
			4.5		0.1	0.26		0.33		
			6.0		0.1	0.26		0.33		
I_{IN}	Input Leakage Current	6.0		± 0.1		± 1.0	μA	$V_{IN} = V_{CC}, \text{ GND}$		
I_{CC}	Quiescent Supply Current	6.0		1.0		10.0	μA	$V_{IN} = V_{CC}, \text{ GND}$		

AC Electrical Characteristics

Symbol	Parameter	V _{CC} (V)	T _A = +25°C			T _A = -40°C to +85°C		Units	Conditions	Figure Number
			Min	Typ	Max	Min	Max			
t _{PLH} , t _{PHL}	Propagation Delay	5.0		3.5	15			ns	C _L = 15 pF	Figures 1, 3
		2.0		20	100		125		C _L = 50 pF	
		3.0		11	27		35	ns		
		4.5		8	20		25			
		6.0		7	17		21			
t _{TLH} , t _{THL}	Output Transition Time	5.0		3.0	10			ns	C _L = 15 pF	Figures 1, 3
		2.0		25	125		155	ns	C _L = 50 pF	
		3.0		16	35		45			
		4.5		11	25		31			
		6.0		9	21		26			
C _{IN}	Input Capacitance	Open		2	10		10	pF		
C _{PD}	Power Dissipation Capacitance	5.0		6				pF	(Note 3)	Figure 2

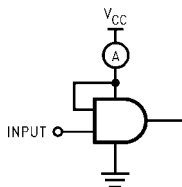
Note 3: C_{PD} is defined as the value of the internal equivalent capacitance which is derived from dynamic operating current consumption (I_{CCD}) at no output loading and operating at 50% duty cycle. (See Figure 2.) C_{PD} is related to I_{CCD} dynamic operating current by the expression:
 $I_{CCD} = (C_{PD})(V_{CC})(f_{IN}) + I_{CCstatic}$.

AC Loading and Waveforms



C_L includes load and stray capacitance
 Input PRR = 1.0 MHz; t_W = 500 ns

FIGURE 1. AC Test Circuit



Input = AC Waveform;
 PRR = variable; Duty Cycle = 50%

FIGURE 2. I_{CCD} Test Circuit

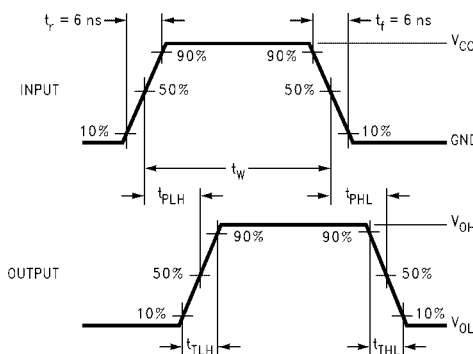


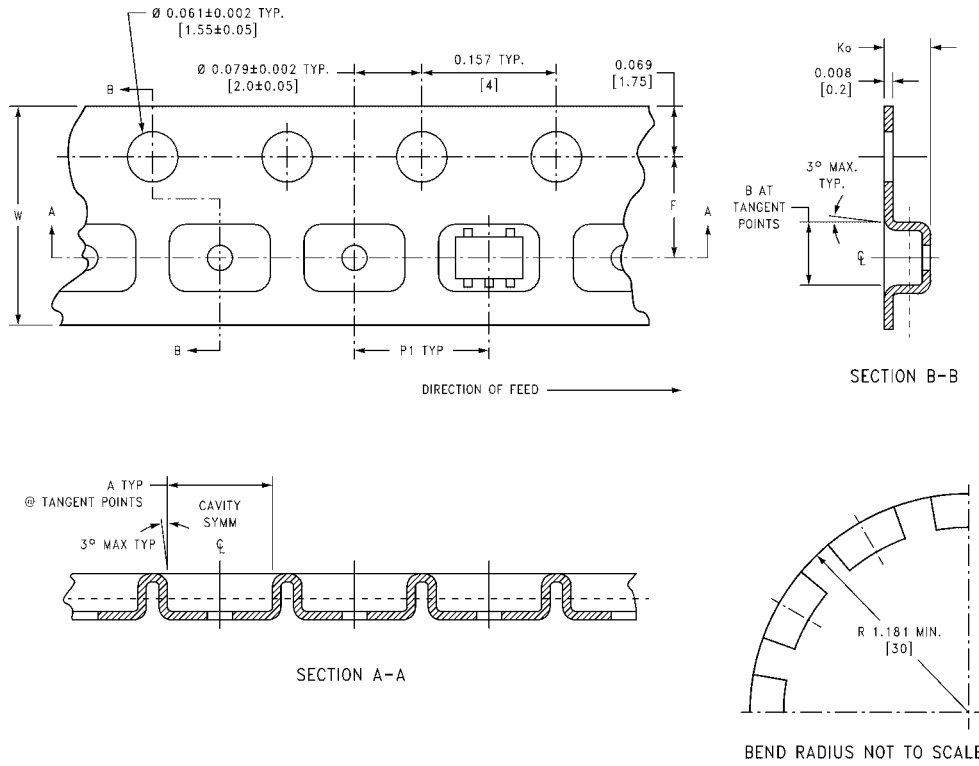
FIGURE 3. AC Waveforms

Tape and Reel Specification

TAPE FORMAT for SC70 and SOT23

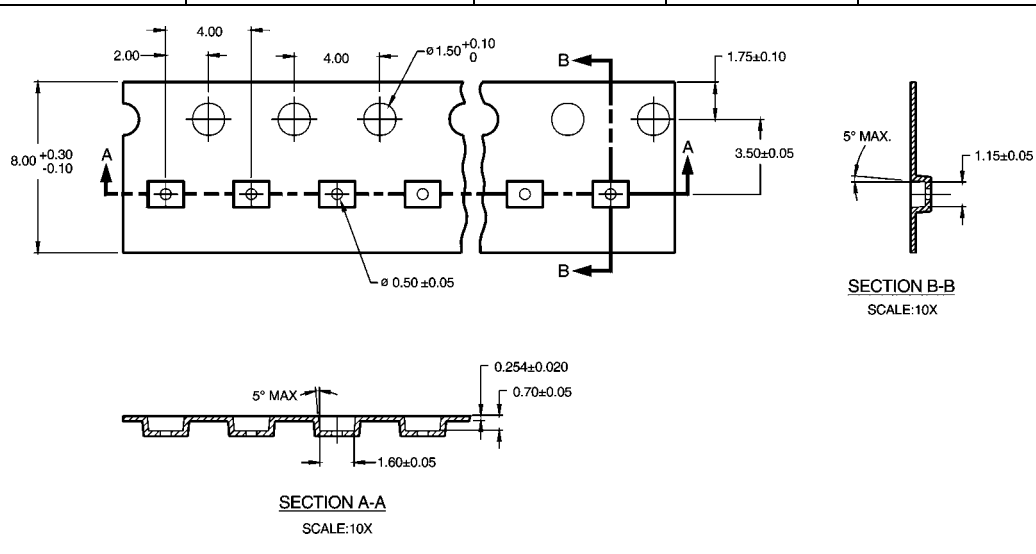
Package Designator	Tape Section	Number Cavities	Cavity Status	Cover Tape Status
M5X, P5X	Leader (Start End)	125 (typ)	Empty	Sealed
	Carrier	3000	Filled	Sealed
	Trailer (Hub End)	75 (typ)	Empty	Sealed

TAPE DIMENSIONS inches (millimeters)

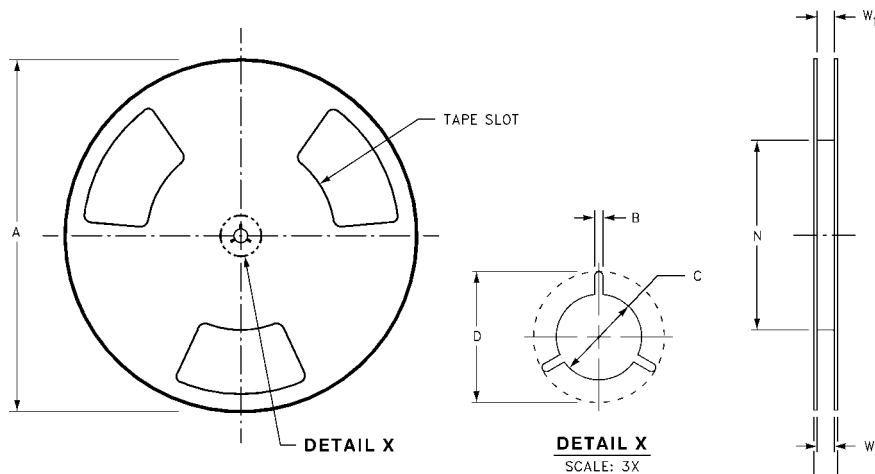


Package	Tape Size	DIM A	DIM B	DIM F	DIM K ₀	DIM P1	DIM W
SC70-5	8 mm	0.093 (2.35)	0.096 (2.45)	0.138 ± 0.004 (3.5 ± 0.10)	0.053 ± 0.004 (1.35 ± 0.10)	0.157 (4)	0.315 ± 0.004 (8 ± 0.1)
SOT23-5	8 mm	0.130 (3.3)	0.130 (3.3)	0.138 ± 0.002 (3.5 ± 0.05)	0.055 ± 0.004 (1.4 ± 0.11)	0.157 (4)	0.315 ± 0.012 (8 ± 0.3)

Tape and Reel Specification (Continued)				
TAPE FORMAT for MicroPak				
Package Designator	Tape Section	Number Cavities	Cavity Status	Cover Tape Status
L6X	Leader (Start End)	125 (typ)	Empty	Sealed
	Carrier	5000	Filled	Sealed
	Trailer (Hub End)	75 (typ)	Empty	Sealed

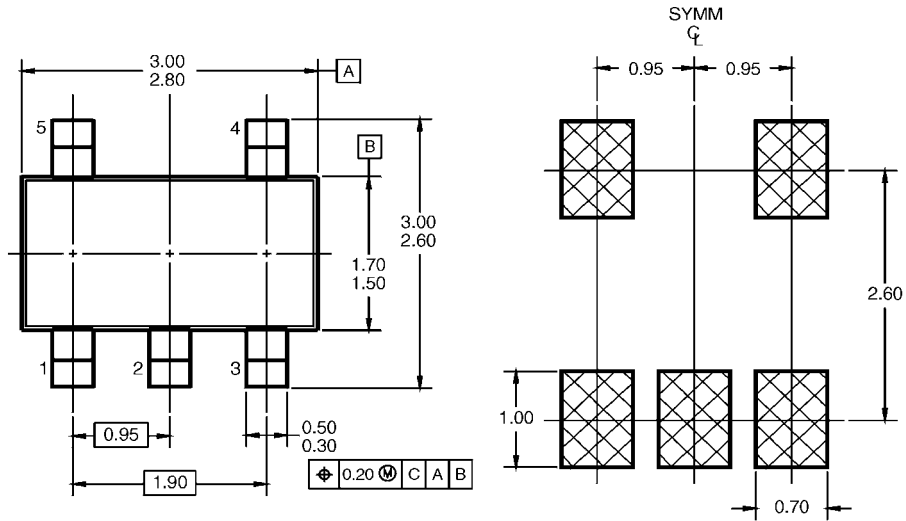


REEL DIMENSIONS inches (millimeters)

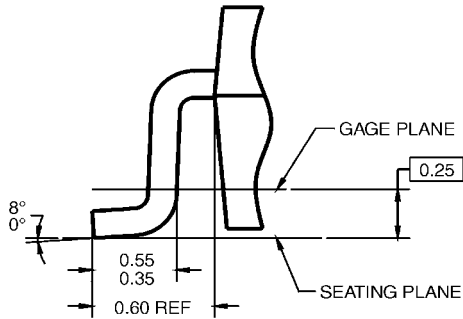
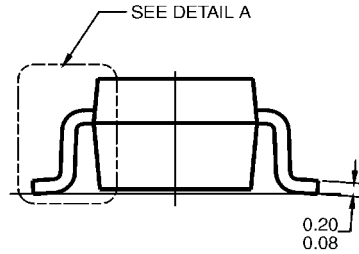
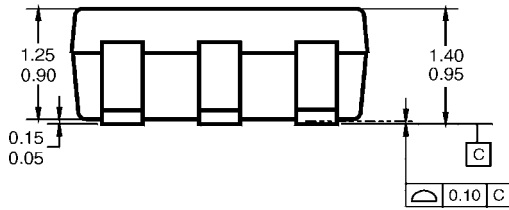


Tape Size	A	B	C	D	N	W1	W2	W3
8 mm	7.0 (177.8)	0.059 (1.50)	0.512 (13.00)	0.795 (20.20)	2.165 (55.00)	0.331 + 0.059/-0.000 (8.40 + 1.50/-0.00)	0.567 (14.40)	W1 + 0.078/-0.039 (W1 + 2.00/-1.00)

Physical Dimensions inches (millimeters) unless otherwise noted



LAND PATTERN RECOMMENDATION



DETAIL A

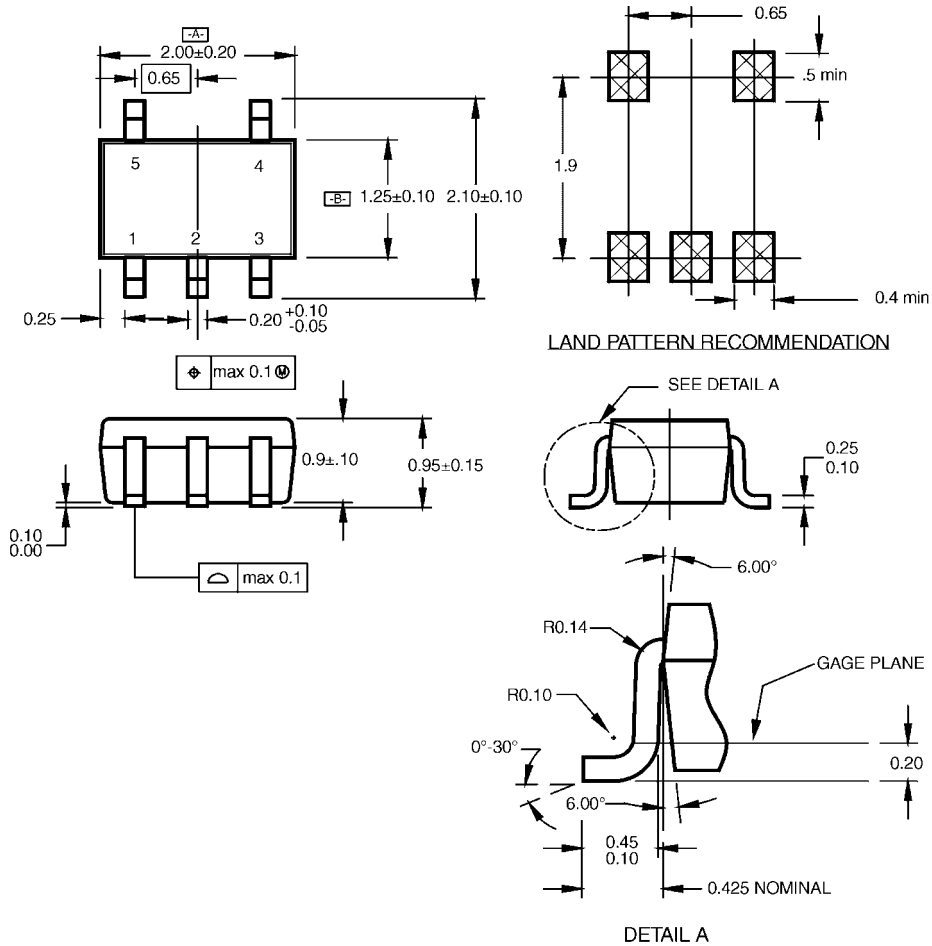
NOTES: UNLESS OTHERWISE SPECIFIED

- A) THIS PACKAGE CONFORMS TO JEDEC MO-178, ISSUE B, VARIATION AA, DATED JANUARY 1999.
- B) ALL DIMENSIONS ARE IN MILLIMETERS.

MA05BRevC

5-Lead SOT23, JEDEC MO-178, 1.6mm
Package Number MA05B

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



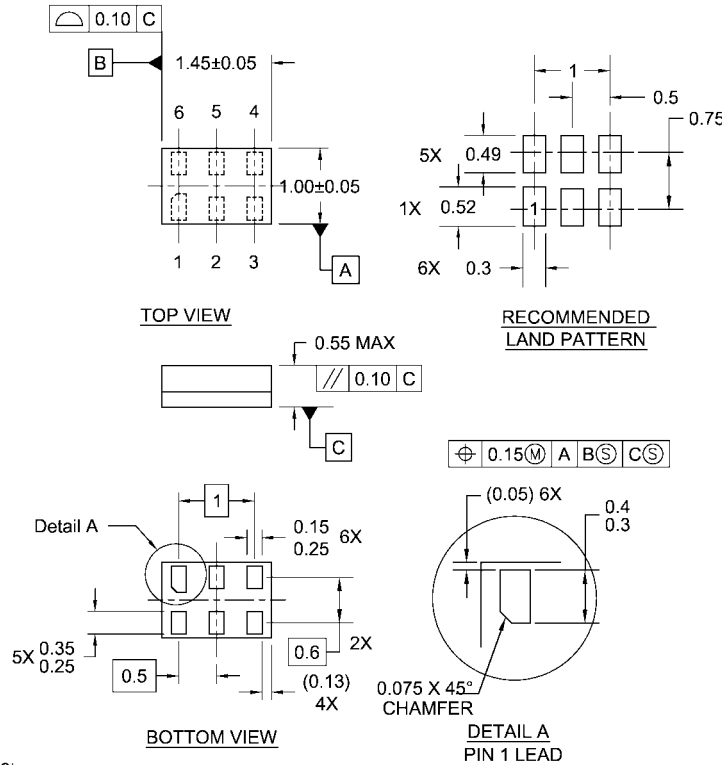
NOTES:

- A. CONFORMS TO EIAJ REGISTERED OUTLINE DRAWING SC88A.
- B. DIMENSIONS DO NOT INCLUDE BURRS OR MOLD FLASH.
- C. DIMENSIONS ARE IN MILLIMETERS.

MAA05ARevC

**5-Lead SC70, EIAJ SC-88a, 1.25mm Wide
Package Number MAA05A**

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



Notes:

1. JEDEC PACKAGE REGISTRATION IS ANTICIPATED
2. DIMENSIONS ARE IN MILLIMETERS
3. DRAWING CONFORMS TO ASME Y14.5M-1994

MAC06ARevB

**6-Lead MicroPak, 1.0mm Wide
Package Number MAC06A**

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